

IMPACT 2015 Call for Papers is OPEN NOW!

Submit Your Abstract Before June 15!

International Microsystems, Packaging, Assembly and Circuits Technology Conference—IMPACT 2015 calls for papers now! The IMPACT Conference is the largest gathering of packaging and PCB professionals in Taiwan, attracting over 4,000 attendees in accumulated total over the past years. Do you have any new discovery or stunning research? Submit your paper to IMPACT 2015 conference before June 15th immediately. It is truly your best access and practice to this new paradigm shift.

To reflect the stable development of flexible electronics technologies and applications. The IMPACT 2015 conference, which will be held in conjunction with TPCA Show and The 6th ICFPE (International Conference on Flexible and Printed Electronics) at Taipei Nangang Exhibition Center on October 21 - 23, 2015, is celebrating its 10th anniversary of bringing worldwide leading experts and engineers together in sharing state-of-the-art advanced microelectronic packaging and PCB technology. The IMPACT Conference is the largest gathering of packaging and PCB professionals in Taiwan, attracting over 4,000 attendees in accumulated total over the past years. As a theme reflects the cutting-edges technology development, the IMPACT Conference highlights “IMPACT on Mobile and Flexible Electronics” . This year, IMPACT Conference not only keeps collaborating with international organizations such as ICEP from Japan and iNEMI from U.S.A , but also invites foreign experts to organize the forums which will focus on IoT and Wearable technologies. We hope this conference will become a remarkable platform to show your technology research and capability.

【Date】 : Oct 21 (Wed)-23(Fri), 2015

【Venue】 : Taipei Nangang Exhibition Center

【Theme】 : IMPACT on Mobile and Flexible Electronics

【Exhibition】 : TPCA Show 2015

【On-line Submission】 : www.impact.org.tw

【SCOPE OF PAPER SOLICITED】

Packaging	PCB
P1. Advanced Packaging Technologies	B1. Green Materials and Process
P2. Green Packaging	B2. Test, Quality, AOI, Inspection and Reliability

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P3. 3D Integration and SiP	B3. HDI and Embedded Technology
P4. LED & Optoelectronics Packaging	B4. Electro Deposition and Electrochemical Processing Technology
P5. Interconnections & Nanotechnology	B5. Advanced and Emerging Technology
P6. Modeling, Simulation & Design	B6. Mechatronics and Automation
P7. Thermal Management	B7. Advanced Materials
P8. Advanced Sensor & Microsystems Technology (MST)	
P9. Advanced Materials, Automatic Process & Assembly	
P10. Emerging Systems Packaging Technologies	

* Papers relevant with the above scopes are encouraged to submit but NOT limited to.

* Conference authority keeps the right to final session arrangement.

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline	June 15, 2015	400-500 words Submit on-line www.impact.org.tw
Abstract Acceptance Notification	July 15, 2015	Notice sent via email
Advance Program Online	August 15, 2015	Advanced program announcement
Full Paper Submission (Camera-ready Version)	August 15, 2015	4 pages including figures and tables Submit on-line through conference website and copyright forms due

* Authors of accepted papers including oral presentation and posters should register before the deadline; please be noted that un-registered (paid) papers will be removed from the symposium program.

* The secretariat keeps the right to modify the agenda.

PAPER AWARD

Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored during the conference.

SPONSOR

IMPACT 2015 sponsors can improve the corporate image, enhance professional development, create networking opportunities and enjoy exclusive benefits. There are multiple sponsorship packages for you to choose!

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IEEE COMPONENTS, PACKAGING, & MANUFACTURING TECHNOLOGY SOCIETY (IEEE

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CPMT-Taipei)

INTERNATIONAL MICROELECTRONICS AND PACKAGING SOCIETY -TAIWAN (IMAPS-Taiwan)

INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE, TAIWAN (ITRI)

TAIWAN PRINTED CIRCUIT ASSOCIATION (TPCA)

CO- ORGANIZER

Communication Research Center, NTU

International Conference on Electronics Packaging (ICEP)

THE INTERNATIONAL ELECTRONICS MANUFACTURING INITIATIVE (iNEMI)

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IMPACT 2015 Secretariat

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